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FOUR DE REFUSION / REFLOW OVEN RK320

Reflow oven RK320



- **Reflow oven RK 320**

- **Technical data**

- **Infared + Air circulation + Air cooling, Pb-free Reflow Oven**

- Surface mounting of units on boards require the exposure of the device package to high temperature to melt the lead finish for board soldering. A lot of the alternative "lead-free" solder materials being considered for use in IC assembly today require a peak soldering temperature of about 250 to 260 deg C, versus the peak temperature of 230 to 235 deg C for Sn-Pb solder. This means that lead-free IC's will need a higher temperature for board mounting, and will therefore be subjected to more severe thermo-mechanical stresses during the process.

- This Oven feature a complete system for today's solder/ Pb-Free solder(260C) requirement. The computer control 20 step range (20 Zone) temperature control allow a smooth and well control temperature curve. High power heating element with force air heating method provide a very even soldering hot zone across the total soldering area, This cost effective unit offer high production count (4-5 mins per cycle of 300mm x 220mm board) which ideal for low to medium size of SMD production. The static soldering process offer very stable non moving especially important for fine pitch SMD soldering.

- **Feature:**

- Infrared Array + Force Air (high volume, low pressure) Heating Method.

- Programmable 20 step control for temperature curve setting.

- Internal cooling fan for fast Cool down performance.

- Fully Automatic, fully static (non moving rail) operation, single or double side board soldering.

- Large transparent glass window see through the soldering process with high temperature build in 35W light (separated ON/OFF) switch.

- Internal complete high gloss stainless steel construction, high IR efficiency and easy to clean, maintenance.

- Ball bearing Rail draw system for stable solder board exchange with minimum vibration.

- Optional PCB tray for quick exchange between the board process.

- Top Open design for quick access to heating element and service.

- Dual channel air circulation. For fast cool down process.

- **Specifications:**

- Maximum heating area: 320mm x 220mm

- Interchangeable tray for continuous process.

- **Maximum Temperature: 290C**

- Operation environment: 0-40C

- Maximum Power consumption: 3.5kW, 1kW Typ.

- Weight: 30kg gross, 40 kg ship

- Dimension: 490mm x 450mm x 345mm

- Input Voltage: 220V single phase